

PRESENT STATUS OF THE CLAIMS SECTION:

Claims 1-12 (canceled)

Claim 13 (previously presented): A method of producing a ceramic thermistor chip, said method comprising the steps of:

stacking a specified number of thermistor ceramic green sheets;

cutting the stacked ceramic green sheets to obtain a ceramic thermistor element having a specific resistance lower than $200\Omega \cdot \text{cm}$ and comprising as principal component oxides containing two or more metals selected from the group consisting of Mn, Ni, Co, Fe, Cu and Al, said ceramic thermistor element having outer surfaces including two end parts away from each other;

applying a ceramic material, having a higher specified resistance than said thermistor ceramic green sheets, entirely over said outer surfaces of said ceramic thermistor element except said end parts, wherein said ceramic material comprises as principal component one or more oxides containing two or more metals selected from the group consisting of Mn, Ni, Co, Fe, Cu and Al and said ceramic material also comprises at least one metal selected from the group consisting of Zn, Al, W, Zr, Sb, Y, Sm, Ti and Fe;

thereafter baking said ceramic thermistor element together with said ceramic material applied thereon; and

thereafter subjecting said baked ceramic thermistor element to an electrolytic plating process to thereby form electrolytically plated layers on said end parts whereby said outer surfaces of said ceramic thermistor element are entirely covered by said high-resistance layer except where said electrolytically plated layers are formed.

Claim 14 (original): The method of claim 13 wherein said ceramic layer and said thermistor element both have a same principal component by 10% or more.

Claim 15 -18 (canceled)